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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	35
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1784-i-p

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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PIC16(L)F1784/6/7



PIC16(L)F1784/6/7

TABLE 3-12: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

	-					(-	/			
Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Ban	k 11-15										
x0Ch or x8Ch to x6Fh or xEFh		Unimplemente	d							_	-

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

1: These registers can be addressed from any bank.

2: Unimplemented, read as '1'.

3: PIC16(L)F1784/7 only.

Note

4: PIC16F1784/6/7 only.

6.6 Register Definitions: Oscillator Control

REGISTER 6-1: OSCCON: OSCILLATOR CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
SPLLEN IRCF<3:0>				_	SCS	<1:0>	
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimpler	nented bit, read	d as '0'	
u = Bit is unc	hanged	x = Bit is unkr	nown	-n/n = Value a	at POR and BC	R/Value at all o	other Resets
'1' = Bit is set	t	'0' = Bit is clea	ared				
bit 7	SPLLEN: So <u>If PLLEN in (</u> SPLLEN bit i <u>If PLLEN in (</u> 1 = 4x PLL I 0 = 4x PLL i	ftware PLL Ena <u>Configuration W</u> s ignored. 4x P <u>Configuration W</u> s enabled s disabled	able bit ′ <u>ords = 1:</u> LL is always e ′ <u>ords = 0:</u>	nabled (subject	t to oscillator re	equirements)	
bit 6-3 IRCF<3:0>: Internal Oscillator Frequency Select bits 1111 = 16 MHz HF or 32 MHz HF ⁽²⁾ 1110 = 8 MHz or 32 MHz HF ⁽²⁾ 1101 = 4 MHz HF 1000 = 2 MHz HF 1011 = 1 MHz HF 1010 = 500 kHz HF ⁽¹⁾ 1001 = 250 kHz HF ⁽¹⁾ 1000 = 125 kHz HF ⁽¹⁾ 1011 = 500 kHz MF (default upon Reset) 0110 = 250 kHz MF 0101 = 125 kHz MF 0101 = 125 kHz MF 0101 = 31.25 kHz HF ⁽¹⁾ 0010 = 31.25 kHz MF							
bit 2 bit 1-0	Unimplemen SCS<1:0>: S 1x = Internal 01 = Timer1 00 = Clock d	nted: Read as ' System Clock S oscillator block oscillator etermined by F	0' elect bits SSC<2:0> in t	Configuration W	Vords.		
Note 1: Du	uplicate frequen	cy derived from	HFINTOSC.				

2: 32 MHz when SPLLEN bit is set. Refer to Section 6.2.2.6 "32 MHz Internal Oscillator Frequency Selection".

9.2 Low-Power Sleep Mode

"F" devices contain an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. "F" devices allow the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

9.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

9.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the normal power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- · External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)
- Note: "LF" devices do not have a configurable Low-Power Sleep mode. "LF" devices are an unregulated device and are always in the lowest power state when in Sleep, with no wake-up time penalty. These devices have a lower maximum VDD and I/O voltage than "F" devices. See Section 30.0 "Electrical Specifications" for more information.

REGISTER I	5-16. ODCO	ND. FURID	UPEN DRAI	. REGISTER	

DECISTED 42.46. ODCOND. DODTD ODEN DDAIN CONTROL DECISTED

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ODB7	ODB6	ODB5	ODB4	ODB3	ODB2	ODB1	ODB0
bit 7							bit 0
Legend:							
R = Readable bit W = Writable bit		bit	U = Unimplemented bit, read as '0'				
u = Bit is unchanged x = Bit is unknown		-n/n = Value at POR and BOR/Value at all other Resets					
'1' = Bit is set		'0' = Bit is clea	ared				

bit 7-0

ODB<7:0>: PORTB Open Drain Enable bits

For RB<7:0> pins, respectively

1 = Port pin operates as open-drain drive (sink current only)

0 = Port pin operates as standard push-pull drive (source and sink current)

REGISTER 13-17: SLRCONB: PORTB SLEW RATE CONTROL REGISTER

| R/W-1/1 |
|---------|---------|---------|---------|---------|---------|---------|---------|
| SLRB7 | SLRB6 | SLRB5 | SLRB4 | SLRB3 | SLRB2 | SLRB1 | SLRB0 |
| bit 7 | | | | | | | bit 0 |

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 SLRB<7:0>: PORTB Slew Rate Enable bits

For RB<7:0> pins, respectively

1 = Port pin slew rate is limited

0 = Port pin slews at maximum rate

REGISTER 13-18: INLVLB: PORTB INPUT LEVEL CONTROL REGISTER

| R/W-0/0 |
|---------|---------|---------|---------|---------|---------|---------|---------|
| INLVLB7 | INLVLB6 | INLVLB5 | INLVLB4 | INLVLB3 | INLVLB2 | INLVLB1 | INLVLB0 |
| bit 7 | | | | | | | bit 0 |

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 INLVLB<7:0>: PORTB Input Level Select bits

For RB<7:0> pins, respectively

1 = ST input used for PORT reads and interrupt-on-change

0 = TTL input used for PORT reads and interrupt-on-change

14.0 INTERRUPT-ON-CHANGE

All pins on all ports can be configured to operate as Interrupt-On-Change (IOC) pins. An interrupt can be generated by detecting a signal that has either a rising edge or a falling edge. Any individual pin, or combination of pins, can be configured to generate an interrupt. The interrupt-on-change module has the following features:

- Interrupt-on-Change enable (Master Switch)
- Individual pin configuration
- Rising and falling edge detection
- Individual pin interrupt flags

Figure 14-1 is a block diagram of the IOC module.

14.1 Enabling the Module

To allow individual pins to generate an interrupt, the IOCIE bit of the INTCON register must be set. If the IOCIE bit is disabled, the edge detection on the pin will still occur, but an interrupt will not be generated.

14.2 Individual Pin Configuration

For each pin, a rising edge detector and a falling edge detector are present. To enable a pin to detect a rising edge, the associated bit of the IOCxP register is set. To enable a pin to detect a falling edge, the associated bit of the IOCxN register is set.

A pin can be configured to detect rising and falling edges simultaneously by setting the associated bits in both of the IOCxP and IOCxN registers.

14.3 Interrupt Flags

The bits located in the IOCxF registers are status flags that correspond to the Interrupt-on-change pins of each port. If an expected edge is detected on an appropriately enabled pin, then the status flag for that pin will be set, and an interrupt will be generated if the IOCIE bit is set. The IOCIF bit of the INTCON register reflects the status of all IOCxF bits.

14.4 Clearing Interrupt Flags

The individual status flags, (IOCxF register bits), can be cleared by resetting them to zero. If another edge is detected during this clearing operation, the associated status flag will be set at the end of the sequence, regardless of the value actually being written.

In order to ensure that no detected edge is lost while clearing flags, only AND operations masking out known changed bits should be performed. The following sequence is an example of what should be performed.

EXAMPLE 14-1: CLEARING INTERRUPT FLAGS (PORTA EXAMPLE)

MOVLW 0xff XORWF IOCAF, W ANDWF IOCAF, F

14.5 Operation in Sleep

The interrupt-on-change interrupt sequence will wake the device from Sleep mode, if the IOCIE bit is set.

If an edge is detected while in Sleep mode, the affected IOCxF register will be updated prior to the first instruction executed out of Sleep.

16.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "Use and Calibration of the Internal Temperature Indicator" (DS01333) for more details regarding the calibration process.

16.1 Circuit Operation

Figure 16-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 16-1 describes the output characteristics of the temperature indicator.

EQUATION 16-1: VOUT RANGES

High Range: VOUT = VDD - 4VT

Low Range: VOUT = VDD - 2VT

The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 15.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for lowvoltage operation.

FIGURE 16-1: TEMPERATURE CIRCUIT DIAGRAM



16.2 Minimum Operating VDD

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 16-1 shows the recommended minimum $V \mbox{\scriptsize DD}$ vs. range setting.

TABLE 16-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0		
3.6V	1.8V		

16.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 17.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

16.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 μ s after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 μ s between sequential conversions of the temperature indicator output.

22.6.2 TIMER1 GATE SOURCE SELECTION

Timer1 gate source selections are shown in Table 22-4. Source selection is controlled by the T1GSS bits of the T1GCON register. The polarity for each available source is also selectable. Polarity selection is controlled by the T1GPOL bit of the T1GCON register.

TABLE 22-4:	TIMER1	GATE	SOURCES
-------------	--------	------	---------

T1GSS	Timer1 Gate Source
00	Timer1 Gate Pin
01	Overflow of Timer0 (TMR0 increments from FFh to 00h)
10	Comparator 1 Output sync_C1OUT (optionally Timer1 synchronized output)
11	Comparator 2 Output sync_C2OUT (optionally Timer1 synchronized output)

22.6.2.1 T1G Pin Gate Operation

The T1G pin is one source for Timer1 gate control. It can be used to supply an external source to the Timer1 gate circuitry.

22.6.2.2 Timer0 Overflow Gate Operation

When Timer0 increments from FFh to 00h, a low-to-high pulse will automatically be generated and internally supplied to the Timer1 gate circuitry.

22.6.2.3 Comparator C1 Gate Operation

The output resulting from a Comparator 1 operation can be selected as a source for Timer1 gate control. The Comparator 1 output (sync_C1OUT) can be synchronized to the Timer1 clock or left asynchronous. For more information see **Section 20.4.1 "Comparator Output Synchronization"**.

22.6.2.4 Comparator C2 Gate Operation

The output resulting from a Comparator 2 operation can be selected as a source for Timer1 gate control. The Comparator 2 output (sync_C2OUT) can be synchronized to the Timer1 clock or left asynchronous. For more information see **Section 20.4.1 "Comparator Output Synchronization**".

22.6.3 TIMER1 GATE TOGGLE MODE

When Timer1 Gate Toggle mode is enabled, it is possible to measure the full-cycle length of a Timer1 gate signal, as opposed to the duration of a single level pulse.

The Timer1 gate source is routed through a flip-flop that changes state on every incrementing edge of the signal. See Figure 22-4 for timing details.

Timer1 Gate Toggle mode is enabled by setting the T1GTM bit of the T1GCON register. When the T1GTM bit is cleared, the flip-flop is cleared and held clear. This is necessary in order to control which edge is measured.

Note:	Enabling Toggle mode at the same time
	as changing the gate polarity may result in
	indeterminate operation.

22.6.4 TIMER1 GATE SINGLE-PULSE MODE

When Timer1 Gate Single-Pulse mode is enabled, it is possible to capture a single-pulse gate event. Timer1 Gate Single-Pulse mode is enabled by first setting the T1GSPM bit in the T1GCON register. Next, the T1GGO/DONE bit in the T1GCON register must be set. The Timer1 will be fully enabled on the next incrementing edge. On the next trailing edge of the pulse, the T1GGO/DONE bit will automatically be cleared. No other gate events will be allowed to increment Timer1 until the T1GGO/DONE bit is once again set in software. See Figure 22-5 for timing details.

If the Single-Pulse Gate mode is disabled by clearing the T1GSPM bit in the T1GCON register, the T1GGO/DONE bit should also be cleared.

Enabling the Toggle mode and the Single-Pulse mode simultaneously will permit both sections to work together. This allows the cycle times on the Timer1 gate source to be measured. See Figure 22-6 for timing details.

22.6.5 TIMER1 GATE VALUE

When Timer1 Gate Value Status is utilized, it is possible to read the most current level of the gate control value. The value is accessible by reading the T1GVAL bit in the T1GCON register. The T1GVAL bit is valid even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

22.6.6 TIMER1 GATE EVENT INTERRUPT

When Timer1 Gate Event Interrupt is enabled, it is possible to generate an interrupt upon the completion of a gate event. When the falling edge of T1GVAL occurs, the TMR1GIF flag bit in the PIR1 register will be set. If the TMR1GIE bit in the PIE1 register is set, then an interrupt will be recognized.

The TMR1GIF flag bit operates even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELB	—	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	138
CCP1CON	—	—	DC1B	<1:0>		CCP1N	1<3:0>		280
CCP2CON	—	—	DC2B	<1:0>		CCP2N	1<3:0>		280
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	93
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	94
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	98
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register						199*		
TMR1L	Holding Regi	ister for the Le	east Significa	nt Byte of the	16-bit TMR1	Register			199*
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	137
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	142
T1CON	TMR1C	S<1:0>	T1CKP	S<1:0>	T1OSCEN	T1SYNC	_	TMR10N	207
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/ DONE	T1GVAL	T1GS	S<1:0>	208

TABLE 22-5:	SUMMARY OF REGISTERS ASSOCIATED WITH TIMER1
-------------	---

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the Timer1 module.

* Page provides register information.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CCP2CON	—		DC2B	<1:0>		CCP2	/ <3:0>		280
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	93
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	94
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	98
PR2	Timer2 Module Period Register						210*		
T2CON	_	T2OUTPS<3:0> TMR2ON T2CKPS<1:0>				212			
TMR2	Holding Register for the 8-bit TMR2 Register						210*		

TABLE 23-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER2

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for Timer2 module.

* Page provides register information.

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
	PxPOLIN	PxPOLF ⁽¹⁾	PxPOLE ⁽¹⁾	PxPOLD ⁽¹⁾	PxPOLC ⁽¹⁾	PxPOLB	PxPOLA
bit 7						bit 0	
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimpler	mented bit, read	as '0'	
u = Bit is uncl	hanged	x = Bit is unkr	nown	-n/n = Value at POR and BOR/Value at all other Res			other Resets
'1' = Bit is set		'0' = Bit is clea	ared				
bit 7	Unimplemen	ted: Read as '	0'				
bit 6	pit 6 PxPOLIN: PSMCxIN Polarity bit						
	1 = PSMCxIN input is active-low						
	0 = PSMCxIN input is active-high						
bit 5-0	bit 5-0 PxPOLy: PSMCx Output y Polarity bit ⁽¹⁾						
	1 = PWM PSMCx output y is active-low						
	0 = PWMP	SMCx output y	is active-high				
Note 1: Th	ese bits are not	implemented of	on PSMC2.				

REGISTER 24-8: PSMCxPOL: PSMC POLARITY CONTROL REGISTER

REGISTER 24-9:	PSMCxBLNK: PSMC BLANKING CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	PxFEBM1	PxFEBM0	_	—	PxREBM1	PxREBM0
bit 7							bit 0

Legend:						
R = Readable bit		W = Writable bit	U = Unimplemented bit, read as '0'			
u = Bit is u	nchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets			
'1' = Bit is s	set	'0' = Bit is cleared				
bit 7-6	Unimplemented: Read as '0'					
bit 5-4	bit 5-4 PxFEBM<1:0> PSMC Falling Edge Blanking Mode bits					
	11 = Reserved – do not use					
	10 = Reserved – do not use					

- 01 = Immediate blanking
- 00 = No blanking
- bit 3-2 Unimplemented: Read as '0'
- bit 1-0 PxREBM<1:0> PSMC Rising Edge Blanking Mode bits
 - 11 = Reserved do not use
 - 10 = Reserved do not use
 - 01 = Immediate blanking
 - 00 = No blanking

U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-1/1
_	—	PxSTRF ⁽²⁾	PxSTRE ⁽²⁾	PxSTRD ⁽²⁾	PxSTRC ⁽²⁾	PxSTRB	PxSTRA
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	as '0'	
u = Bit is uncha	anged	x = Bit is unkr	iown	-n/n = Value a	at POR and BOF	R/Value at all c	ther Resets
'1' = Bit is set		'0' = Bit is clea	ared				
bit 7-6	Unimplemen	tad: Pead as '	،				
bit 5		M Steering PSI		Enable hit(2)			
bit 5		:0> = 0000 (Si	nale-nhase Pl				
	1 = Single P	WM output is a	active on pin P	/ <u>/////.</u> /SMCxF			
	0 = Single P	WM output is r	not active on p	in PSMCxF. P	WM drive is in in	active state	
	If PxMODE<3	:0> = 0001 (C	omplementary	Single-phase	<u>PWM):</u>		
	1 = Complete0 = Complete	mentary PWM	output is active	e on pin PSMC ctive on nin PS	CXF SMCxOUT5 PW	/M drive is in i	nactive state
	IF PxMODE<	3.0 > = 1100 (3)	-nhase Steerij	ייייע און			
	1 = PSMCx[D and PSMCxE	are high. PS	MCxA, PMSC	xB, PSMCxC and	d PMSCxF are	e low.
	0 = 3-phase	output combin	ation is not ac	tive			
bit 4	PxSTRE: PW	M Steering PS	MCxE Output	Enable bit ⁽²⁾			
	If PxMODE<3	<u>:0> = 000x (sin</u>	<u>ngle-phase PV</u>	VM or Comple	mentary PWM):		
	1 = Single P 0 = Single P	WM output is a	not active on pin P	INCXE	WM drive is in ir	nactive state	
	IF PxMODE<	3:0> = 1100 (3	-phase Steerii	na): ⁽¹⁾			
	1 = PSMCxE	3 and PSMCxE	are high. PSI	MCxA, PMSC>	C, PSMCxD and	d PMSCxF are	e low.
	0 = 3-phase	output combin	ation is not ac	tive			
bit 3	PxSTRD: PW	M Steering PS	MCxD Output	Enable bit ⁽²⁾			
	$\frac{\text{If PxMODE}<3}{1 = \text{Single P}}$: <u>:0> = 0000 (Si</u> WM output is a	<u>ngle-phase Pl</u> active on pin P	<u>//M):</u> /SMCxD			
	0 = Single P	WM output is r	not active on pin r	in PSMCxD. F	WM drive is in ir	nactive state	
	If PxMODE<3	:0> = 0001 (Ce	omplementary	single-phase	<u>PWM):</u>		
	1 = Compler	mentary PWM	output is active	e on pin PSMC			
			putput is not a	ctive on pin Pa	SINCXD. PVVIVI di	rive is in inacti	ve state
	1 = PSMCxE	$3.0^{2} = 1100$ (3) B and PSMCx(are high. PS	<u>ig).</u> MCxA. PMSC:	xD. PSMCxE and	d PMSCxF are	e low.
	0 = 3-phase	output combin	ation is not ac	tive	,		
bit 2	PxSTRC: PW	M Steering PS	MCxC Output	Enable bit ⁽²⁾			
	If PxMODE<3	:0> = 000x (Si	ngle-phase P\	NM or Comple	ementary PWM):		
	1 = Single P	WM output is a	active on pin P		N/M drivo is in ir	pactivo stato	
		$\frac{1}{3.0} = 1100$	nhase Steerin	יוו רטויוטגט. ד _{ממ} ן.(1)		Idelive Slale	
	1 = PSMCx(C and PSMCxF	are high. PSI	ري. MCxA, PMSC>	B, PSMCxD and	d PMSCxE are	e low.
	0 = 3-phase	output combin	ation is not ac	tive			

REGISTER 24-31: PSMCxSTR0: PSMC STEERING CONTROL REGISTER 0

26.6.4 I²C MASTER MODE START CONDITION TIMING

To initiate a Start condition, the user sets the Start Enable bit, SEN bit of the SSPCON2 register. If the SDA and SCL pins are sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<7:0> and starts its count. If SCL and SDA are both sampled high when the Baud Rate Generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low while SCL is high is the Start condition and causes the S bit of the SSPSTAT1 register to be set. Following this, the Baud Rate Generator is reloaded with the contents of SSPADD<7:0> and resumes its count. When the Baud Rate Generator times out (TBRG), the SEN bit of the SSPCON2 register will be automatically cleared by hardware; the Baud Rate Generator is suspended, leaving the SDA line held low and the Start condition is complete.

the SDA and SCL pins are already sampled low, or if during the Start condition, the SCL line is sampled low before the SDA line is driven low, a bus collision occurs, the Bus Collision Interrupt Flag, BCL1IF, is set, the Start condition is aborted and the I²C module is reset into its Idle state.

Note 1: If at the beginning of the Start condition,

2: The Philips I²C specification states that a bus collision cannot occur on a Start.

FIGURE 26-26: FIRST START BIT TIMING



26.6.5 I²C MASTER MODE REPEATED START CONDITION TIMING

A Repeated Start condition occurs when the RSEN bit of the SSPCON2 register is programmed high and the master state machine is no longer active. When the RSEN bit is set, the SCL pin is asserted low. When the SCL pin is sampled low, the Baud Rate Generator is loaded and begins counting. The SDA pin is released (brought high) for one Baud Rate Generator count (TBRG). When the Baud Rate Generator times out, if SDA is sampled high, the SCL pin will be deasserted (brought high). When SCL is sampled high, the Baud Rate Generator is reloaded and begins counting. SDA and SCL must be sampled high for one TBRG. This action is then followed by assertion of the SDA pin (SDA = 0) for one TBRG while SCL is high. SCL is asserted low. Following this, the RSEN bit of the SSP- CON2 register will be automatically cleared and the Baud Rate Generator will not be reloaded, leaving the SDA pin held low. As soon as a Start condition is detected on the SDA and SCL pins, the S bit of the SSPSTAT register will be set. The SSP1IF bit will not be set until the Baud Rate Generator has timed out.

- Note 1: If RSEN is programmed while any other event is in progress, it will not take effect.
 - **2:** A bus collision during the Repeated Start condition occurs if:
 - SDA is sampled low when SCL goes from low-to-high.
 - SCL goes low before SDA is asserted low. This may indicate that another master is attempting to transmit a data '1'.





26.6.8 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN bit of the SSPCON2 register. When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCL pin is deasserted (pulled high). When the SCL pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSP module then goes into Idle mode (Figure 26-29).

26.6.8.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write does not occur).

26.6.9 STOP CONDITION TIMING

A Stop bit is asserted on the SDA pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN bit of the SSPCON2 register. At the end of a receive/transmit, the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the Baud Rate Generator is reloaded and counts down to '0'. When the Baud Rate Generator times out, the SCL pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDA pin will be deasserted. When the SDA pin is sampled high while SCL is high, the P bit of the SSPSTAT register is set. A TBRG later, the PEN bit is cleared and the SSP1IF bit is set (Figure 26-30).

26.6.9.1 WCOL Status Flag

If the user writes the SSPBUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

FIGURE 26-30: ACKNOWLEDGE SEQUENCE WAVEFORM



ADDLW	Add literal and W
Syntax:	[<i>label</i>] ADDLW k
Operands:	$0 \le k \le 255$
Operation:	$(W) + k \to (W)$
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal 'k' and the result is placed in the W register.

ANDLW	AND literal with W
Syntax:	[<i>label</i>] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .AND. (k) \rightarrow (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W reg- ister.

ADDWF	Add W and f						
Syntax:	[label] ADDWF f,d						
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$						
Operation:	(W) + (f) \rightarrow (destination)						
Status Affected:	C, DC, Z Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.						
Description:							

ANDWF	AND W with f					
Syntax:	[<i>label</i>] ANDWF f,d					
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$					
Operation:	(W) .AND. (f) \rightarrow (destination)					
Status Affected:	Z					
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.					

ADDWFC	ADD W and CARRY bit to f					
Syntax:	[label] ADDWFC f {,d}					
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$					
Operation:	$(W) + (f) + (C) \rightarrow dest$					
Status Affected:	C, DC, Z					
Description:	Add W, the Carry flag and data memory location 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location 'f'					

ASRF	Arithmetic Right Shift
Syntax:	[label] ASRF f {,d}
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f<7>)→ dest<7> (f<7:1>) → dest<6:0>, (f<0>) → C,
Status Affected:	C, Z
Description:	The contents of register 'f' are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.

	register f	→ X	
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FIGURE 30-11: CAPTURE/COMPARE/PWM TIMINGS (CCP)



TABLE 30-12: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP)

Standard Operating Conditions (unless otherwise stated)								
Param No.	Sym.	Characteris	stic	Min.	Тур†	Max.	Units	Conditions
CC01*	TccL	CCPx Input Low Time	No Prescaler	0.5Tcy + 20			ns	
			With Prescaler	20	-	-	ns	
CC02*	TccH	CCPx Input High Time	No Prescaler	0.5Tcy + 20	-	-	ns	
			With Prescaler	20	-	-	ns	
CC03*	TccP	CCPx Input Period		<u>3Tcy + 40</u> N	—	—	ns	N = prescale value (1, 4 or 16)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS					
	Dimension Limits	MIN	NOM	MAX			
Number of Leads	N		44				
Lead Pitch	е		0.80 BSC				
Overall Height	А	_	_	1.20			
Molded Package Thickness	A2	0.95	1.00	1.05			
Standoff	A1	0.05	_	0.15			
Foot Length	L	0.45	0.60	0.75			
Footprint	L1		1.00 REF				
Foot Angle	ф	0°	3.5°	7°			
Overall Width	E		12.00 BSC				
Overall Length	D	12.00 BSC					
Molded Package Width	E1	10.00 BSC					
Molded Package Length	D1	10.00 BSC					
Lead Thickness	С	0.09 – 0					
Lead Width	b	0.30	0.37	0.45			
Mold Draft Angle Top	α	11°	12°	13°			
Mold Draft Angle Bottom	β	11° 12° 13°					

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

- 2. Chamfers at corners are optional; size may vary.
- 3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (06/2012)

Initial release.

Revision B (11/2012)

Minor updates.

Revision C (08/2014)

Change from Preliminary to Final data sheet.

Corrected the following Tables: Family Types Table on page 3, Table 3-3, Table 3-8, Table 20-3, Table 22-2, Table 22-3, Table 23-1, Table 25-3, Table 30-1, Table 30-2, Table 30-3, Table 30-6, Table 30-7, Table 30-13, Table 30-14, Table 30-15, Table 30-16, Table 30-20.

Corrected the following Sections: Section 3.2, Section 9.2, Section 13.3, Section 17.1.6, Section 15.1, Section 15.3, Section 17.2.5, Section 18.2, Section 18.3, Section 19.0, Section 22.6.5, Section 22.9, Section 23.0, Section 23.1, Section 24.2.4, Section 24.2.5, Section 24.2.7, Section 24.8, Section 25.0, Section 26.6.7.4, Section 30.3.

Corrected the following Registers: Register 4-2, Register 8-2, Register 8-5, Register 17-3, Register 18-1, Register 24-3, Register 24-4.

Corrected Equation 17-1.

Corrected Figure 30-9. Removed Figure 24-21.